

## INTERFLUX® ELECTRONICS NV TECHNICAL DATA



# INTERFLUX® Total Solution TS 33

#### **DESCRIPTION:**

TS33 is a synthetic no-clean flux. TS33 is developed to allow a wide-open process window for the no-clean solderingprocess. Since no-clean fluxes are not developed to be cleaned, TS33 is especially made to be compatible with solvent based cleaners for those who still want or need to clean (part of) their production for specific reasons. The excellent soldering performance reduces the process costs and improves the quality. TS33 meets Bell-core and IPC requirements.

## **APPLICATION:**

TS33 can be applied by foam, spray, wave or dipping. Use an airknife after foamfluxing. On the preheating the PCB should reach between 80°C and 120°C on topside. A solderwave set-up where oxides are pushed over the backplate when the PCB reaches the solderwave, is recommended.

The solderability of TS33 on pretinned or OSP coated bare copper boards is excellent. For soldering on bare copper, please consult also the Interflux<sup>7</sup> publications on this issue.

Any residues (transparent!) that would occur, can easily be removed with Isopropanol or with solvent based cleaners.

## **PHYSICAL AND CHEMICAL PROPERTIES:**

Flash point (T.O.C.) : +13°C Odour : Aliphatic alcohol

Recommended thinner : T1000 conditioner

## **HEALTH & SAFETY:**

Material Safety Datasheets available upon request.

#### **PACKAGING:**

10L, 25L and 200 Liter high density polyethylene drums.

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